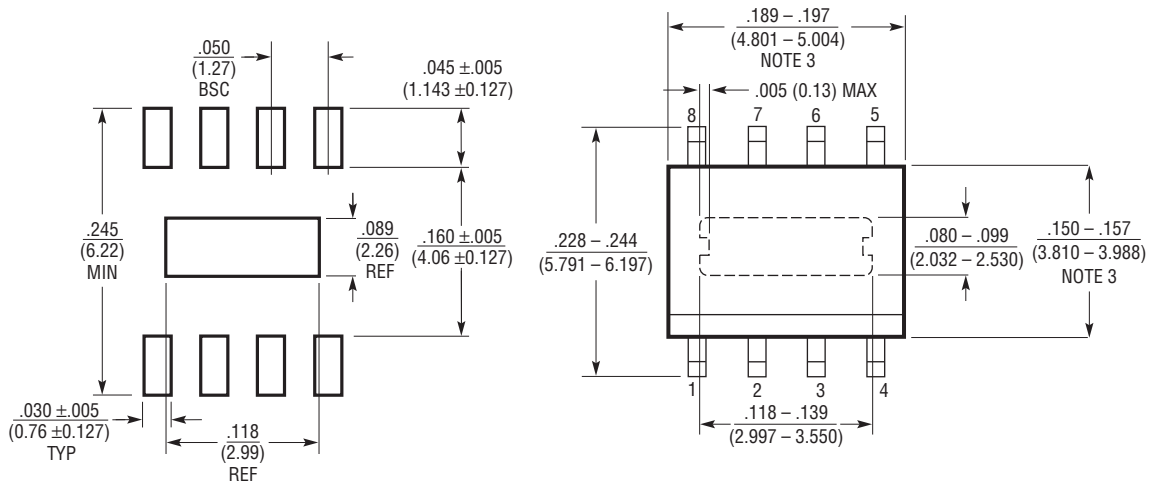
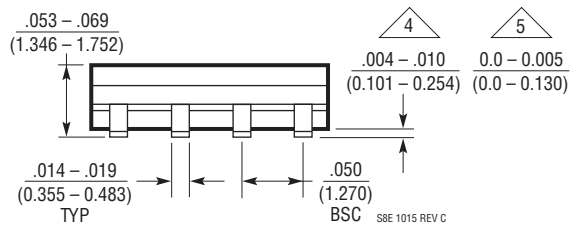
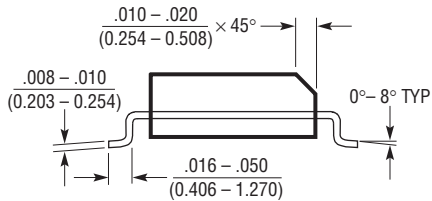


S8E Package
8-Lead Plastic SOIC (Narrow .150 Inch) Exposed Pad
 (Reference LTC DWG # 05-08-1857 Rev C)



RECOMMENDED SOLDER PAD LAYOUT



- NOTE:
 1. DIMENSIONS IN $\frac{\text{INCHES}}{\text{MILLIMETERS}}$
 2. DRAWING NOT TO SCALE
 3. THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010" (0.254mm)

4. STANDARD LEAD STANDOFF IS 4mils TO 10mils (DATE CODE BEFORE 542)
 5. LOWER LEAD STANDOFF IS 0mils TO 5mils (DATE CODE AFTER 542)